# PRODUCT/PROCESS CHANGE NOTICE (PCN)

**PCN #:** A1910-01  
**DATE:** 29-Oct-2019  
**Product Affected:** FCCSP-53, FCCSP-253  
(Refer to attachment II for affected part#)

**Date Effective:** 29-Jan-2020

**Contact:** PCN DESK

**E-mail:** idt-pcn@lm.renesas.com

**Attachment:** Yes

**Samples:** N/A

## MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
- Back Mark  
- Date Code
- Other  
- Traceable through lot#  

## DESCRIPTION AND PURPOSE OF CHANGE:

- **Die Technology**
- **Wafer Fabrication Process**
- **Assembly Process**
- **Equipment**
- **Material**
- **Testing**
- **Manufacturing Site**
- **Data Sheet**
- **Other**

This notification is to advise our customers that Sample Open/Short test will be introduced at Assembly Process at Amkor Korea and Stats Chippac, Korea at the request of the customers.

Attachment I details the process flow.

Attachment II lists the affected part numbers.

## RELIABILITY/QUALIFICATION SUMMARY:

N/A

## CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

**Customer:**

**Name/Date:**

**Title:**

**E-Mail Address:**

**Phone# /Fax# :**

**Approval for shipments prior to effective date.**

**CUSTOMER COMMENTS:**

________________________

**IDT ACKNOWLEDGMENT OF RECEIPT:**

**RECD. BY:**

**DATE:**
PCN Type: Assembly Process
Data Sheet Change: None
No change in moisture sensitivity level (MSL)

Detail Of Change:
This notification is to advise our customers that Sample Open/Short test will be introduced at Assembly Process at Amkor Korea and Stats Chippac, Korea at the request of the customers.

Assembly process flow as detailed below.

Assembly Sample Open/Short Test and 3-sigma Trigger Limit Disposition Flow

Bumping Issue: Missing bumps, Open bumps, UBM Defects, RDL defects.
Assembly Issue: Bump bridge, Missing bump, Delamination, Die Crack.
Substrate Issue: Shorting Trace, Open Trace, Open Via.
### Affected Part Numbers

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Part Number</th>
<th>Part Number</th>
<th>Part Number</th>
</tr>
</thead>
<tbody>
<tr>
<td>4DB0226EMKB0AVG</td>
<td>4DB0226KB0AVG8</td>
<td>4RCD0124KC0ATGI</td>
<td>4RCD0232EMKC1ATG8</td>
</tr>
<tr>
<td>4DB0226EMKB0AVG8</td>
<td>4DB0232KC2AVG</td>
<td>4RCD0124KC0ATGI8</td>
<td>4RCD0232KC1ATG</td>
</tr>
<tr>
<td>4DB0226KA3AVG</td>
<td>4DB0232KC2AVG8</td>
<td>4RCD0229KB1ATG</td>
<td>4RCD0232KC1ATG8</td>
</tr>
<tr>
<td>4DB0226KA3AVG8</td>
<td>4RCD0124KC0ATG</td>
<td>4RCD0229KB1ATG8</td>
<td>X026LP1AVG</td>
</tr>
<tr>
<td>4DB0226KB0AVG</td>
<td>4RCD0124KC0ATG8</td>
<td>4RCD0232EMKC1ATG</td>
<td>X026LP1AVG8</td>
</tr>
</tbody>
</table>